

Amendments to the Specification:

Please amend the paragraph beginning at line 19 of page 6 as follows:

Again in FIG. 3, the chip (die) 22 and the substrate 20 are interconnected by means of signal transferring means such as bonding wires 26, which can be, for example, gold wires. Actually, the die 22 is connected to the conductive traces of the substrate 20. Using conventional wire bonding or some other techniques, the chip 22 is coupled to the conductive traces. As aforesaid, the conductive traces are on the substrate for providing electrical connective paths. One end of the bonding wire 26 is connected to the chip 22 via a conductive pad formed thereon, the other end of the bonding wire 26 is connected to a solder ball of a BGA array 28 formed on the lower-sided surface (second major surface) of the substrate 20 via the conductive traces 20.

Amendments to the Title:

Please amend the title appearing at lines 1 and 2 of page 1 as follows:

~~STRUCTURE OF HEAT SLUG-EQUIPPED PACKAGES AND THE~~
~~PACKAGING METHOD OF THE SAME~~
SEMICONDUCTOR PACKAGE FOR EFFICIENT HEAT SPREADING